

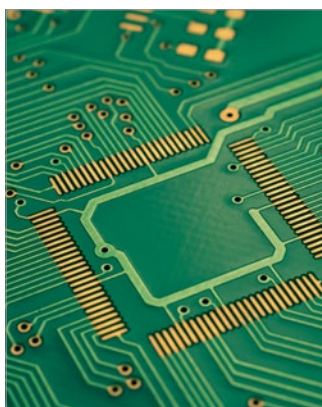


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# AURUNA® 5000

## FINE GOLD ELECTROLYTE



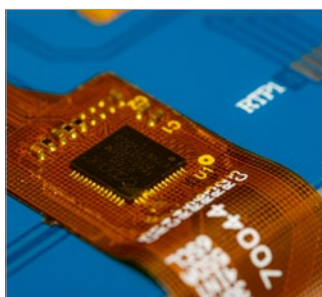
### Fine gold coatings with very good bonding and soldering properties

AURUNA® 5000 is a neutral fine gold electrolyte for the deposition of matt yellow, fine crystalline gold coatings. It is designed for use on flexible printed circuit boards, but can also be used without any limitations on rigid substrates.

AURUNA® 5000 coatings have a fineness of over 99.95% and a hardness of 70 - 85 HV 0.025, which means they comply with the ASTM B488 - 01 Type III Code A/B classification.

The printed circuit boards are plated in a matt nickel bath before gold plating, pre-gold plated and then coated with AURUNA® 5000. The result is gold layers with excellent bondability and solderability, high ductility and low electrical resistance.

The electrolyte is extremely easy to handle and is characterised by impressive longevity.



### Advantages

- High power yield
- Resist-friendly operating conditions
- Excellent bondability and solderability
- Low hardness, low contact resistance
- ASTM B488 - 01 Type III Code A/B
- Easy handling
- High longevity

### Applications

- Flexible and rigid printed circuit boards

# AURUNA<sup>®</sup> 5000

## FINE GOLD ELECTROLYTE

### TECHNICAL SPECIFICATIONS

Electrolyte characteristics		Coating characteristics	
Electrolyte type	neutral	Coating	Fine gold
Metal content	6 (5 - 9) g/l Au	Purity	> 99,95 % Au
pH value	6.0 (5.8 - 6.2)	Colour of deposit	matt yellow
Operating temperature	65 (62 - 68) °C	Hardness of deposit	≤ 85 HV 0.025 (≤ 90 HK 0.025)
Current density range	0.3 (0.1 - 0.5) A/dm <sup>2</sup>		
Plating speed	approx. 0.17 µm/min at 0.3 A/dm <sup>2</sup>		

### YOUR CONTACT

Do you have a specific question or would you like a no-obligation quote calculation?  
Our specialist will be happy to help you with any technical questions you might have.



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